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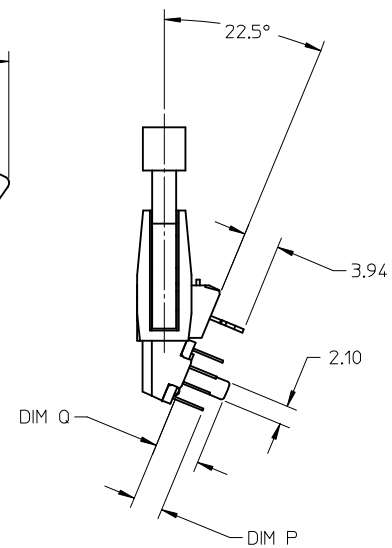
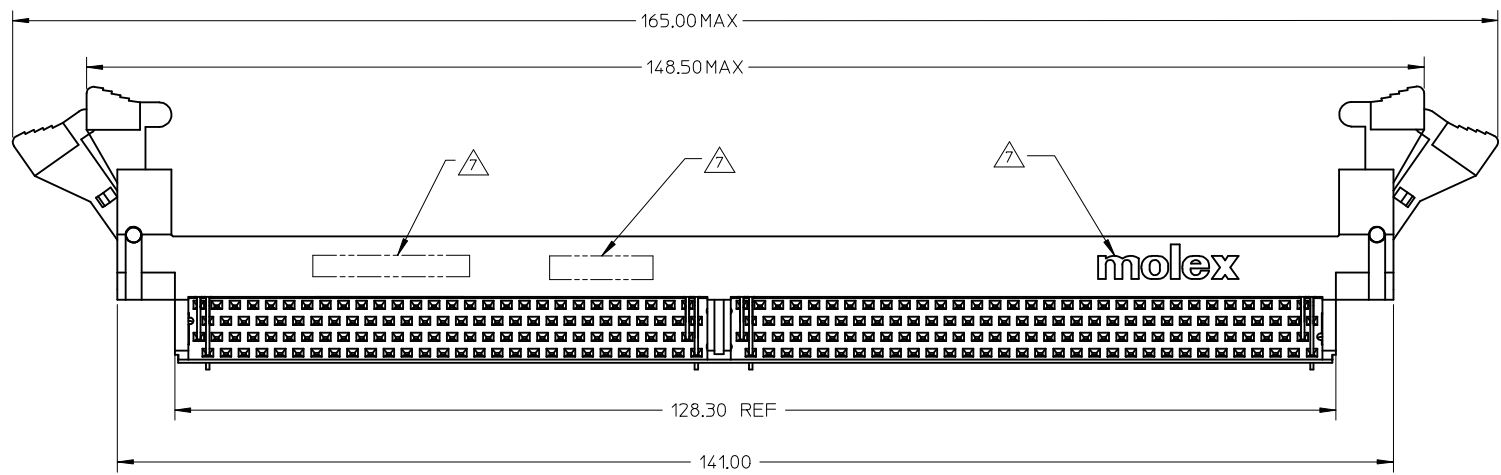
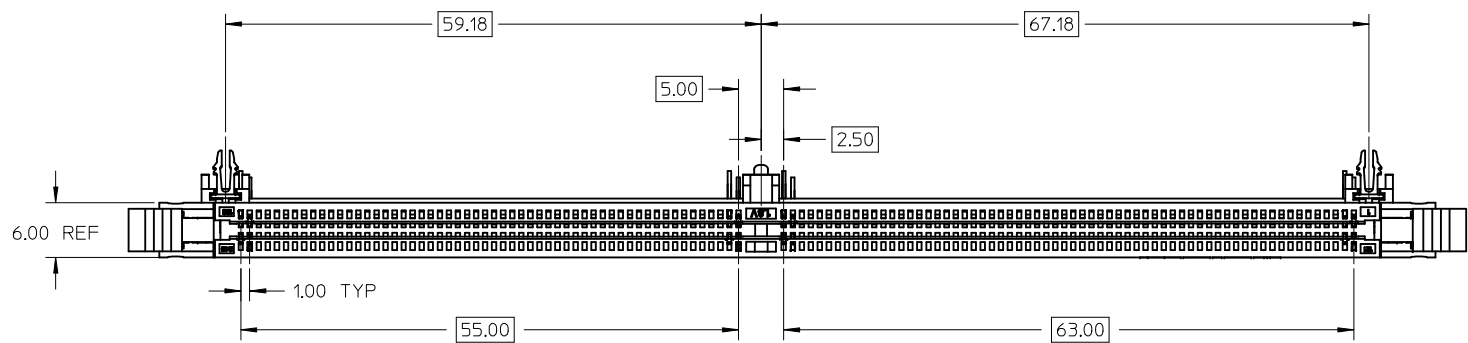
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Rev. E 2006/04/15

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- NOTES :
1. MATERIALS : HOUSING, BASEPLATE AND LATCH.
- HIGH TEMP THERMOPLASTIC, UL94-0.
TERMINALS & FORKLOCK - COPPER ALLOY.
 2. PLATING : CONTACT AREA - SEE TABLE IN SHEET 5.
SOLDERTAIL - SEE TABLE IN SHEET 5.
 3. CARD SLOT ACCEPTS 1.27+/-0.10MM MODULE THICKNESS
(MEASURED OVER PC PADS).
 4. REFER TO PRODUCT SPECIFICATION , PS-87916-001 FOR
PERFORMANCE SPECIFICATION.
 5. RECOMMENDED MODULE CARD LAYOUT SHALL BE AS PER JEDEC MO-237.
 6. PRODUCT SHALL BE PACKED IN TRAY.
- △ MOLEX LOGO, DATE CODE & PART NUMBER INDICATED ON HOUSING.

ADDED OPTION EC NO: S2008-0329 2007/10/24 DRW:NCCTEH CHKD:XYANG01 APPR:SHLENI 2007/10/25	DESCRIPTION	QUALITY SYMBOLS ▽=0 ◇=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION ⊙ ⊞		
				mm	INCH	DRAWN BY JTAN	DATE 2004/05/11	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 22.5 DEG			
			4 PLACES	± ---	± ---	CHECKED BY MLONG	DATE 2004/06/11				
			3 PLACES	± ---	± ---	APPROVED BY GGLLEE	DATE 2004/06/11	MOLEX INCORPORATED			
			2 PLACES	± 0.25	± ---	MATERIAL NO.					
A1	REV		ANGULAR ± 5 °		SEE TABLE		SD-87916-001		1 OF 5		
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

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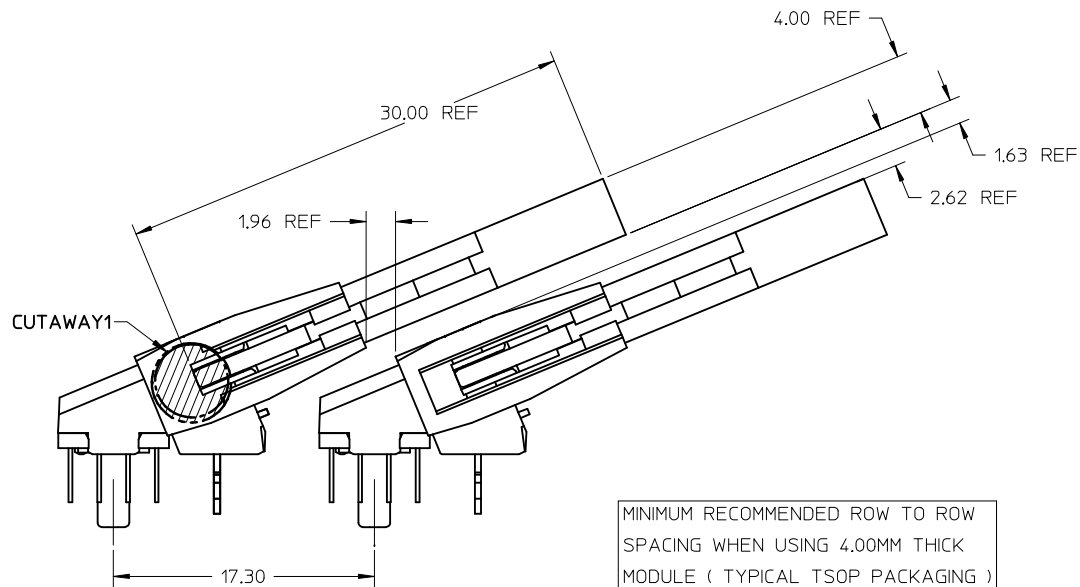
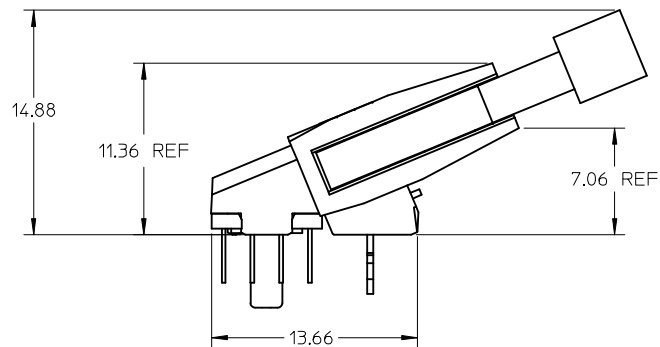
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ADDED OPTION EC NO: S2008-0329 DRWN:CCTEH CHKD:YTYANG01 APPR:SHLENI A1	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
					MM ONLY		NTS	METRIC	
					DRAWN BY	DATE	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 22.5 DEG		
					JTAN	2004/05/11			
					CHECKED BY	DATE			
		MLONG	2004/06/11	MOLEX INCORPORATED					
		APPROVED BY	DATE						
		GGLEE	2004/06/11	DOCUMENT NO.		SHEET NO.			
		ANGULAR ± 5 °		SD-87916-001		2 OF 5			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

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PART NO.	VOLTAGE KEY	DIM 'P'	DIM 'Q'	RECOMMENDED PCB THICKNESS	CONTACT AREA PLATING	SOLDERTAIL PLATING
87916-0001	1.8V	2.79	3.18	1.57	0.76μM/ 30u" GOLD OVER 1.27μM/ 50u" MIN NICKEL	2.54μM/ 100u" MIN. TIN OVER 1.27μM/ 50u" MIN NICKEL
87916-0011		3.18	4.83	2.36		
87916-0111		4.00		3.20		

ADDED OPTION EC NO: S2008-0329 DRWN:CCTEH 2007/10/24 CHKD:YTYANG01 2007/10/24 APPR:SHEN1 2007/10/25	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
				mm	INCH	DRAWN BY JTAN		DATE 2004/05/11		TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 22.5 DEG	
			4 PLACES	± ---	± ---	CHECKED BY		DATE			
			3 PLACES	± ---	± ---	MLONG		2004/06/11			
			2 PLACES	± 0.25	± ---	APPROVED BY		DATE			
		1 PLACE		± ---	± ---	GGLLEE		2004/06/11		MOLEX INCORPORATED	
		ANGULAR ± 5 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-87916-001		5 OF 5			
A1		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									